



Q. Metrology, Inspection, and Yield Enhancement 분과

2019년 2월 15일(금), 15:30-17:15

Room K (국실, 5층)

[FK3-Q] Nanoanalysis and Characterization

좌장: 박병천 박사(KRISS), 양준모 박사(나노종합기술원)

<p>FK3-Q-1 15:30-15:45</p>	<p><b>In-Line Sidewall Roughness Metrology by 3d Atomic Force Microscope</b> Jong-Hyeok Park<sup>1</sup>, Sang-Joon Cho<sup>1</sup>, Byung-Woon Ahn<sup>1</sup>, Tae-Gon Kim<sup>2</sup>, and Sang-il Park<sup>1</sup> <i><sup>1</sup>Park Systems Corp, <sup>2</sup>Imec vzw, Belgium</i></p>
<p>FK3-Q-2 15:45-16:15</p>	<p>[초청] <b>Optical Characterization of Semiconductor Surfaces and Interfaces: Photoluminescence and Raman Spectroscopy</b> Woo Sik Yoo <i>WaferMasters, Inc</i></p>
<p>FK3-Q-3 16:15-16:30</p>	<p><b>Leakage Characteristics for CMP Slurries Using GOI Pattern Wafer</b> Jongyoung Cho, Kijung Kimm, Changji Han, and Hyungsoon Park <i>Division of Research and Development, SK Hynix</i></p>
<p>FK3-Q-4 16:30-16:45</p>	<p><b>FEG(Field Emission Gun)를 장착한 외기형 SEM의 응용사례 연구</b> 구정희, 강전진, 김선희 <i>Seron Technologies Inc</i></p>
<p>FK3-Q-5 16:45-17:15</p>	<p>[초청] <b>Quantitative Mapping of Charge and Strain by Electron Holography</b> Sang Ho Oh <i>Department of Energy Science, Sungkyunkwan University</i></p>